## 1. Part No. Expression:

<u>Z 1 M 1 0 0</u> - <u>R M</u> -□

(a)(b)(c) (d) (e)(f) (g)

(a) Series Code

(e) R: Reel

(b) Dimension Code

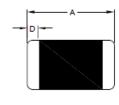
(f) Rated Current

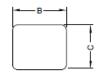
(c) Material Code

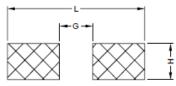
(g) Internal Control Number

(d) Impedance Code

# 2. Configuration & Dimensions:







Recommended PC Board Pattern

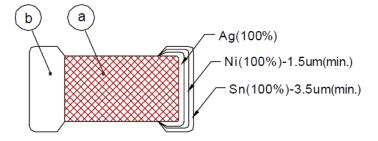
Unit: mm

Α	В	С	D	G	Н	L
1.00 ± 0.10	0.50 ± 0.10	0.50 ± 0.10	0.25 ± 0.10	0.40 Ref.	0.55 Ref.	1.50 Ref.

### 3. Schematic



## 4. Material List



(a) Body: Ferrite

(b) Termination: Ag/Ni/Sn

NOTE: Specifications subject to change without notice. Please check our website for latest information.



## 5. General Specification

a) Operating Temperature: - 40°C to +125°C (including self-temperature rise)

b) Storage Condition (component in its packaging)

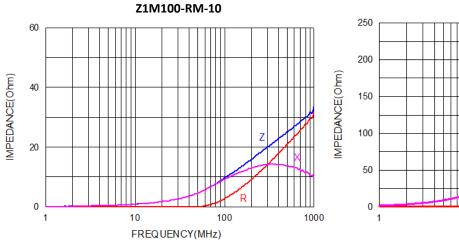
i) Temperature: Less than 40°C

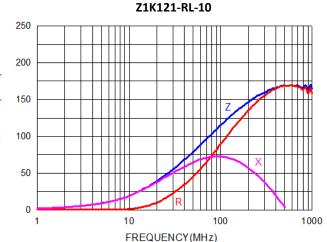
ii) Humidity: 60% RH

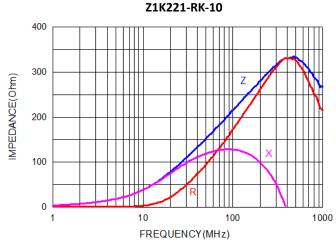
## 6. Electrical Characteristics

Part No.	Impedance (Ω)	Test Frequency (MHz)	DCR (Ω) Max.	Rated Current (mA) Max.
Z1M100-RM-10	10 ± 25%	100	0.05	2500
Z1K121-RL-10	120 ± 25%	100	0.095	2000
Z1K221-RK-10	220 ± 25%	100	0.15	1500

## 7. Characteristics Curves







NOTE: Specifications subject to enange without notice. Please eneck our website for latest information.



### 8. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

#### Note:

If wave soldering is used, there will be some risk.

Re-flow soldering temperatures below 240°C, there will be non-wetting risk

#### 8-1.1 Solder Re-flow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1.

### 8-1.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

#### Note:

- a) Preheat circuit and products to 150°C.
- b) 350°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 secs.

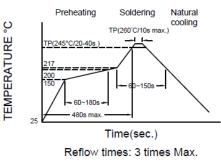
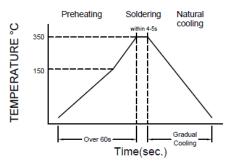


Fig.1



Iron Soldering times: 1 times Max.

Fig.2

#### 8-1.3 Soldering Volume:

Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceeding as shown in the Figure 3. Minimum fillet height = soldering thickness + 25% product height.

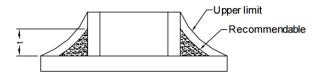
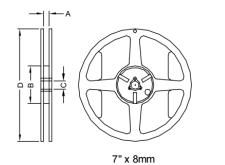


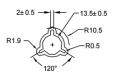
Figure 3
NOTE: Specifications subject to change without notice. Please check our website for latest information.



# 9. Packaging Information

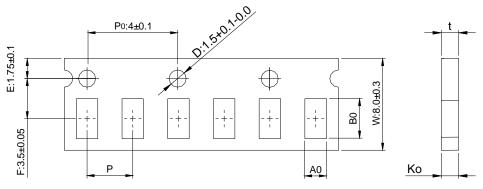
#### 9-1. Reel Dimension





Туре	A (mm)	B (mm)	C (mm)	D (mm)
7" x 8mm	$9.0 \pm 0.5$	60.0 ± 2.0	13.5 ± 0.5	178.0± 2.0

## 9-2. Tape Dimension



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
Z1	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03

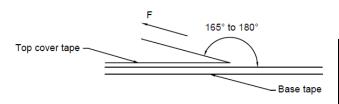
### 9-3. Packaging Quantity

Size	Z1		
Chip/ Reel	10,000		
Inner Box	50,000		
Middle Box	250,000		
Carton	500,000		

NOTE: Specifications subject to change without notice. Please check our website for latest information.



### 9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp Room Humidity (%)			m atm nPa)	Tearing Speed (mm/min)	
5 - 35	45	860	- 1060	300	

# **Application Notice:**

### 1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

#### 2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.